

## Electronic Patent Application Fee Transmittal

<b>Application Number:</b>	10761690
<b>Filing Date:</b>	20-Jan-2004
<b>Title of Invention:</b>	SYSTEM AND METHOD FOR ACHIEVING PLANAR ALIGNMENT OF A SUBSTRATE DURING SOLDER BALL MOUNTING FOR USE IN SEMICONDUCTOR FABRICATION
<b>First Named Inventor:</b>	Art Bayot
<b>Filer:</b>	Yingsheng Tung/Jackie McBride
<b>Attorney Docket Number:</b>	TI-33355A

Filed as Large Entity

### **Utility Filing Fees**

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Basic Filing:</b>				
<b>Pages:</b>				
<b>Claims:</b>				
<b>Miscellaneous-Filing:</b>				
<b>Petition:</b>				
<b>Patent-Appeals-and-Interference:</b>				
<b>Post-Allowance-and-Post-Issuance:</b>				
Utility Appl issue fee	1501	1	1400	1400
Publ. Fee- early, voluntary, or normal	1504	1	300	300

Description	Fee Code	Quantity	Amount	Sub-Total in USD(\$)
<b>Extension-of-Time:</b>				
<b>Miscellaneous:</b>				
<b>Total in USD (\$)</b>				1700